P002



## DOCKET NO. KHASELEV 1-1-7

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Khaselev, O.

Serial No.:

10/050,013

Filed:

January 17, 2002

Title:

Electroplating solution for high speed plating of tin-copper solder

Gtp./A.U.:

1753

Examiner:

Edna Wong

Commissioner for Patents P.Q. Box 1450

Alexandria, VA 22313-1450

Sir:

## AMENDMENT UNDER 37 C.F.R. § 1.116

In response to the Examiner's Action mailed March 8, 2004, please accept the following amendments and remarks.